

form: A4mmXLc

1

2

PDS: Rev :F 3

FF

7

F

FF

10 11

F | F | F

5

F

12 STATUS:Released

F F

FFFF

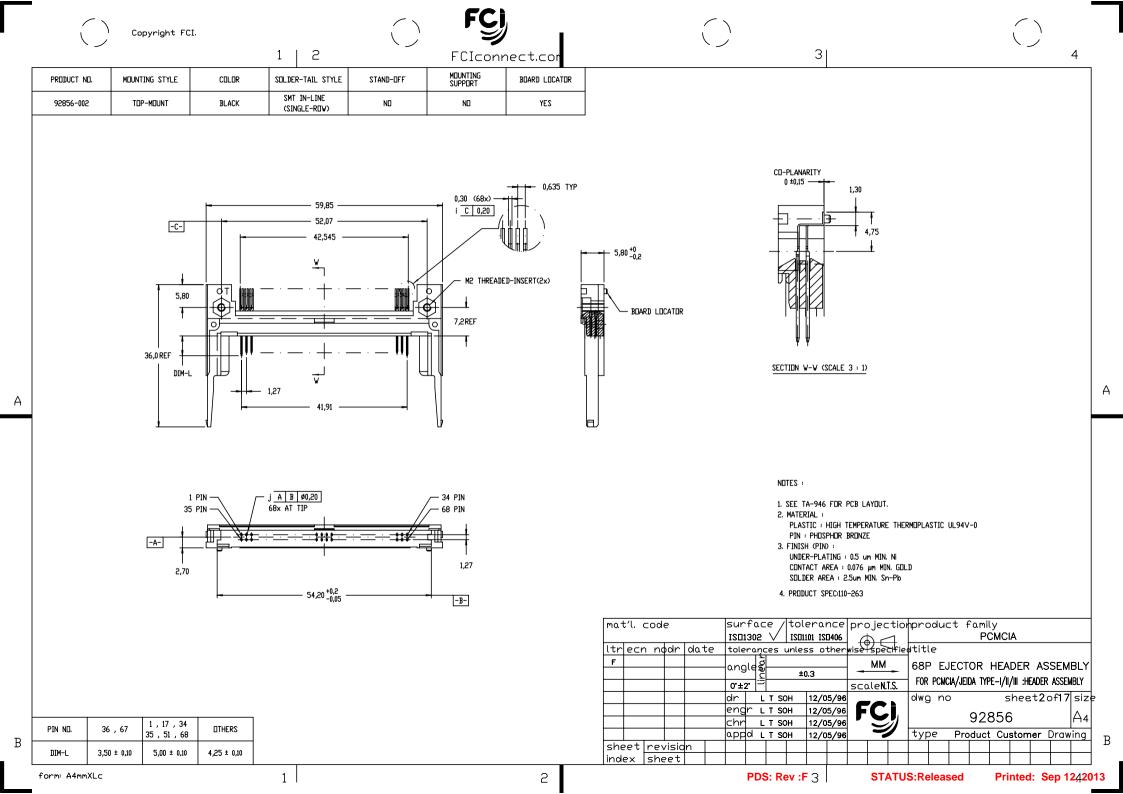
16 17

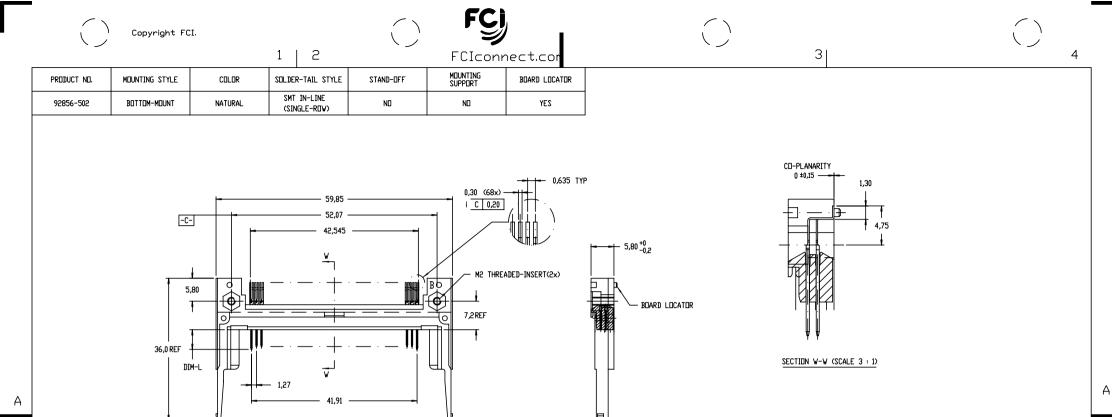
13 14 15

Printed: Sep 1242013

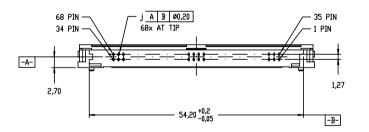
sheet revision F | F |

index |sheet|





2



ma	t'l. d	ode	5			sur	fai	_e /	tol	era	nce	projectionproduct family											
						ISO	302	\vee	ISO1	101 IS	□406		<u> </u>	1	PCMCIA								
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						0°±	0°±2° ≤			0.3		sco	aleN.	T.S.	FOR	FOR PCMCIA/JEIDA TYPE-I/II/III :HEADER ASSE						ASSEM	IBLY
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she	et	rev	/isio	n																			
ind	ex	she	et																				

NOTES :

1. SEE TA-946 FOR PCB LAYDUT.

2. MATERIAL :

PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 PIN : PHOSPHOR BRONZE

3. FINISH (PIN):

UNDER-PLATING : 0.5 um MIN. NI CONTACT AREA : 0.076 µm MIN. GOLD SOLDER AREA : 2.5um MIN. Sn-Pb

4. PRODUCT SPEC:110-263

PIN ND. 36 , 67 1 , 17 , 34 35 , 51 , 68 DTHERS

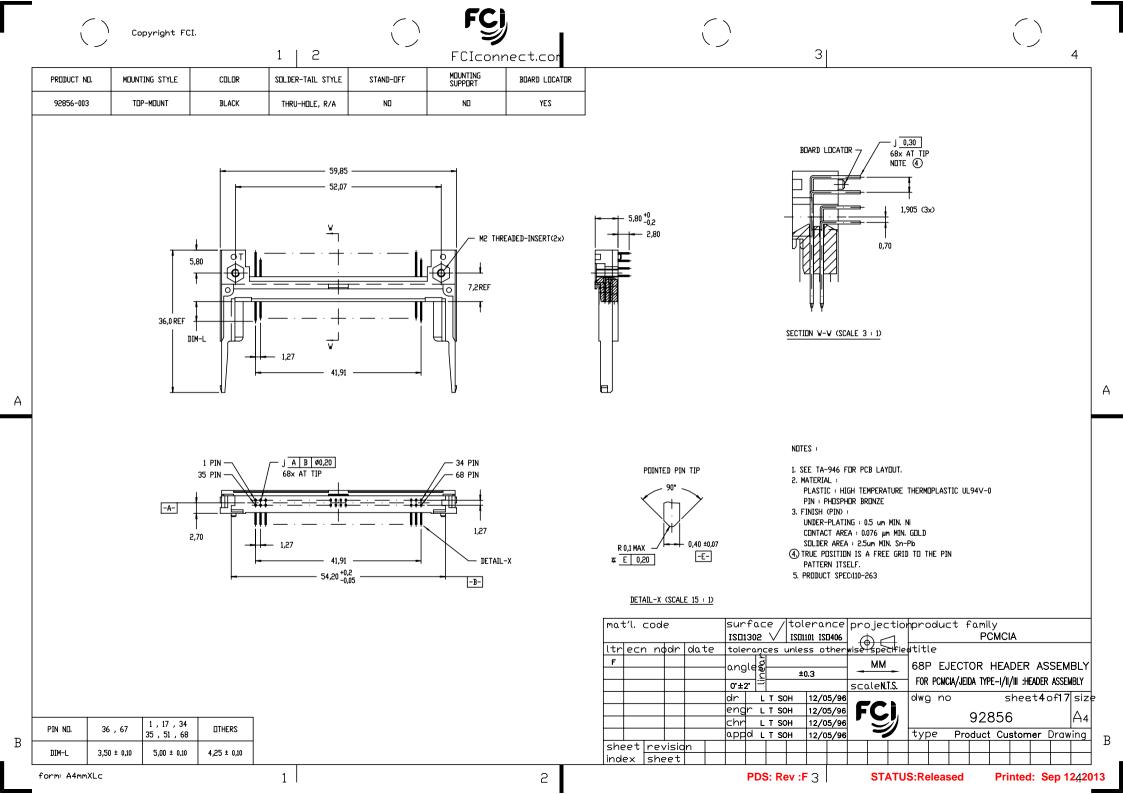
DIM-L 3,50 ± 0,10 5,00 ± 0,10 4,25 ± 0,10

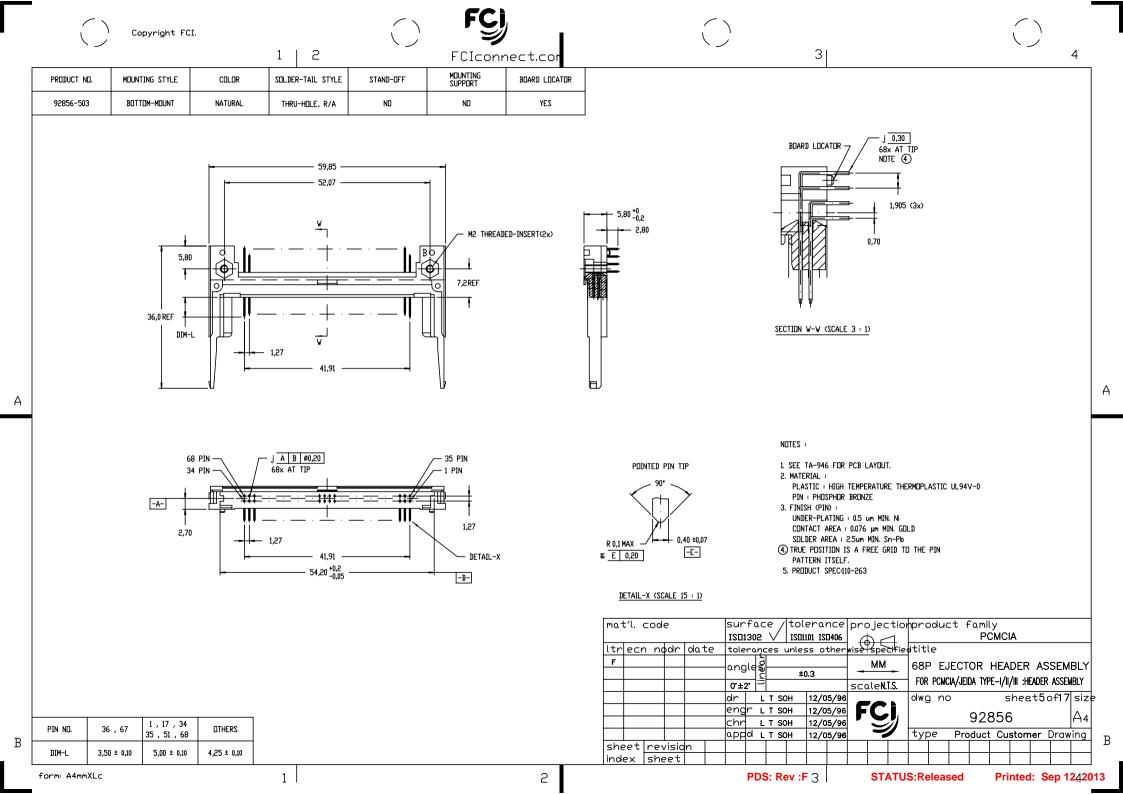
form: A4mmXLc 1

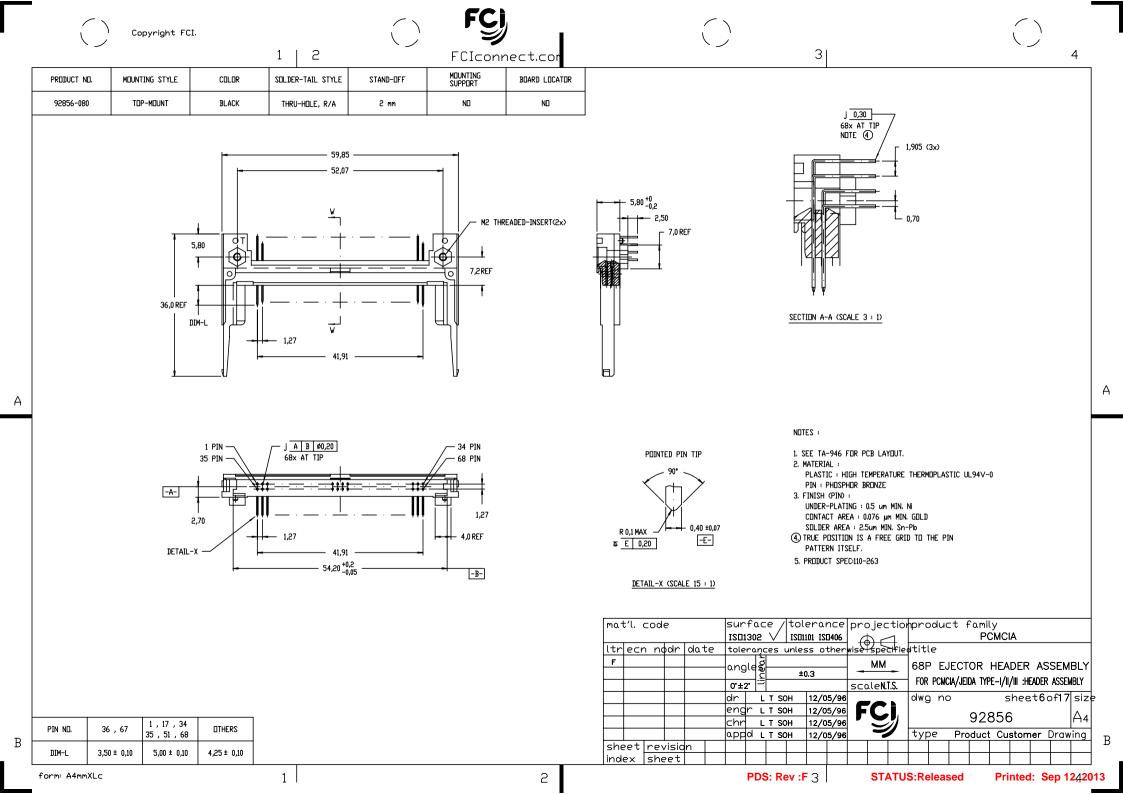
PDS: Rev :F 3

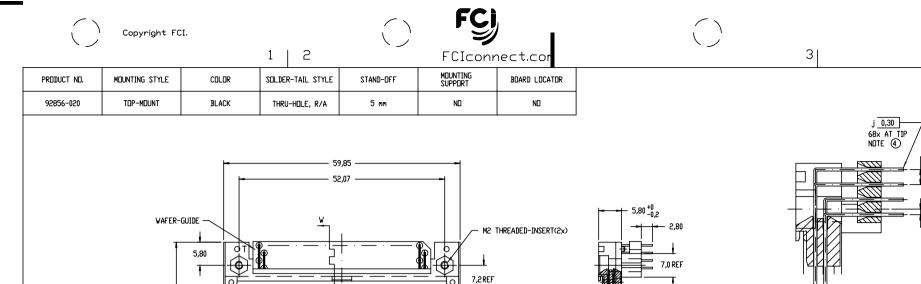
STATUS:Released

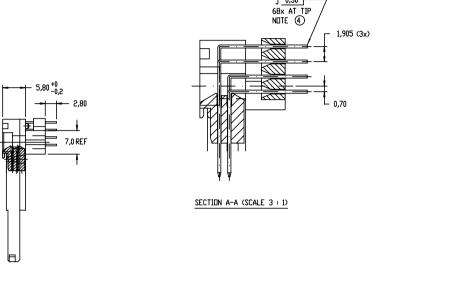
Printed: Sep 1242013

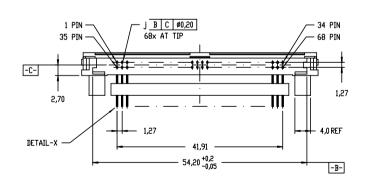






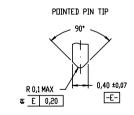






41,91

1,27



NOTES :

- 1. SEE TA-946 FOR PCB LAYDUT.
- 2. MATERIAL : PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 PIN : PHOSPHOR BRONZE
- 3. FINISH (PIN) : UNDER-PLATING : 0.5 um MIN. Ni CONTACT AREA: 0.076 µm MIN. GOLD SOLDER AREA : 2.5um MIN. Sn-Pb (4) TRUE POSITION IS A FREE GRID TO THE PIN
- PATTERN ITSELF.
- 5. PRODUCT SPEC:110-263

DETAIL-X	(SCALE	15	:	1)

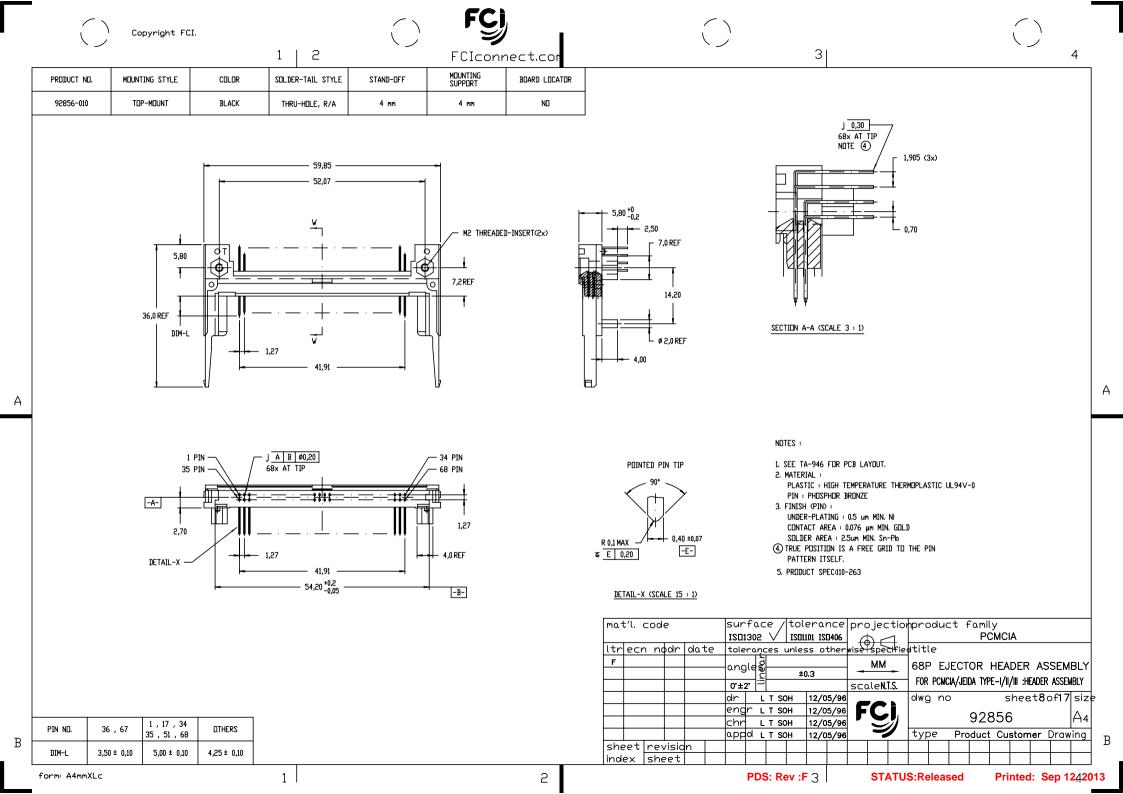
mat	t'l. c	ode				sur						projection product family											
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						eng	rι	. T S	ЮН	12/0	5/96	F	C	. i					o E d				١,
						chr	L	. T S	ЮН	12/0	5/96	•	9.					92	2856 <i>[</i>				
						app	dι	. T S	ЮН	12/0	5/96	4 <i></i> //			typ	type		duct	: Cu	stom	er	Drav	/in
she	et	revi	sia	n																			
inde	ex [she	sheet																				

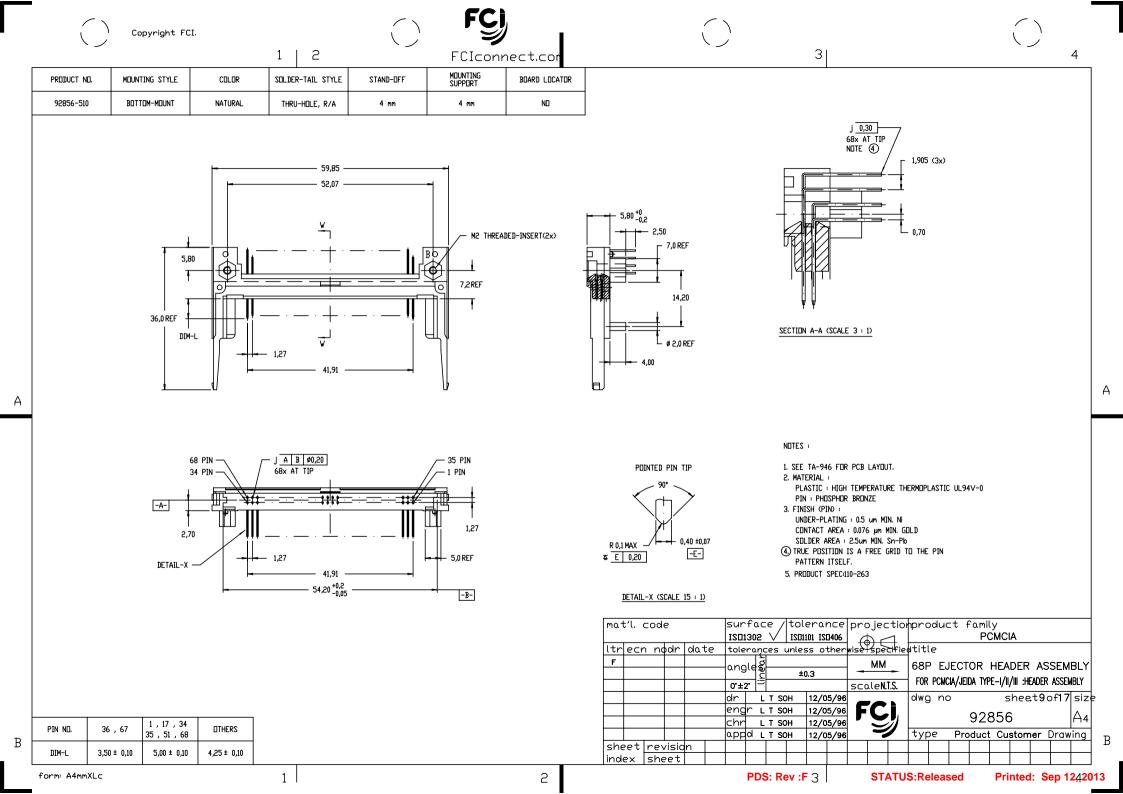
1 , 17 , 34 PIN ND. 36,67 DTHERS 35 , 51 , 68 3,50 ± 0,10 DIM-L 5,00 ± 0,10 4,25 ± 0,10

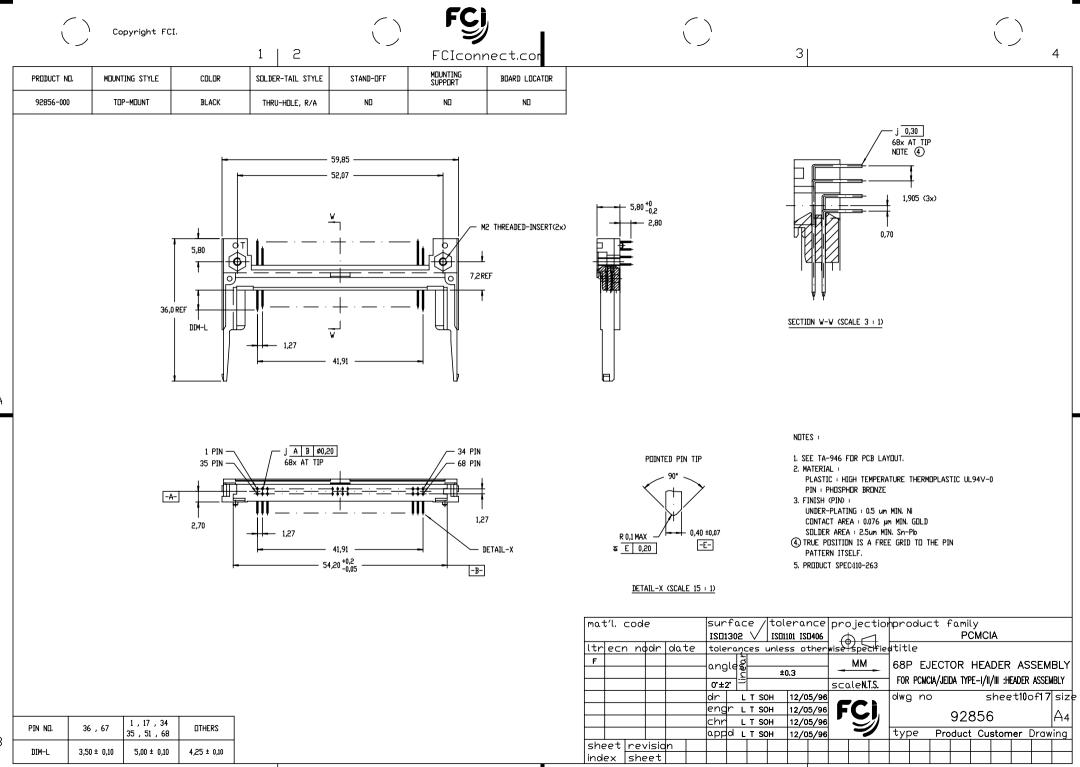
form: A4mmXLc

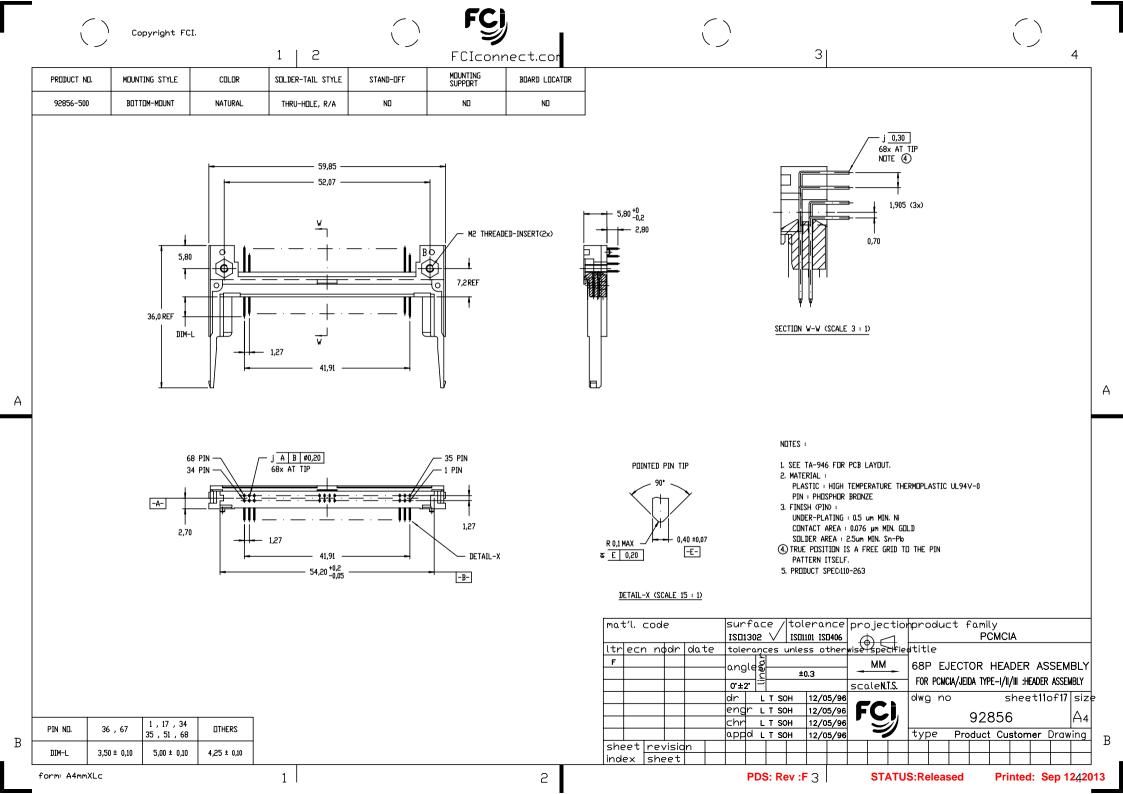
36,0 REF

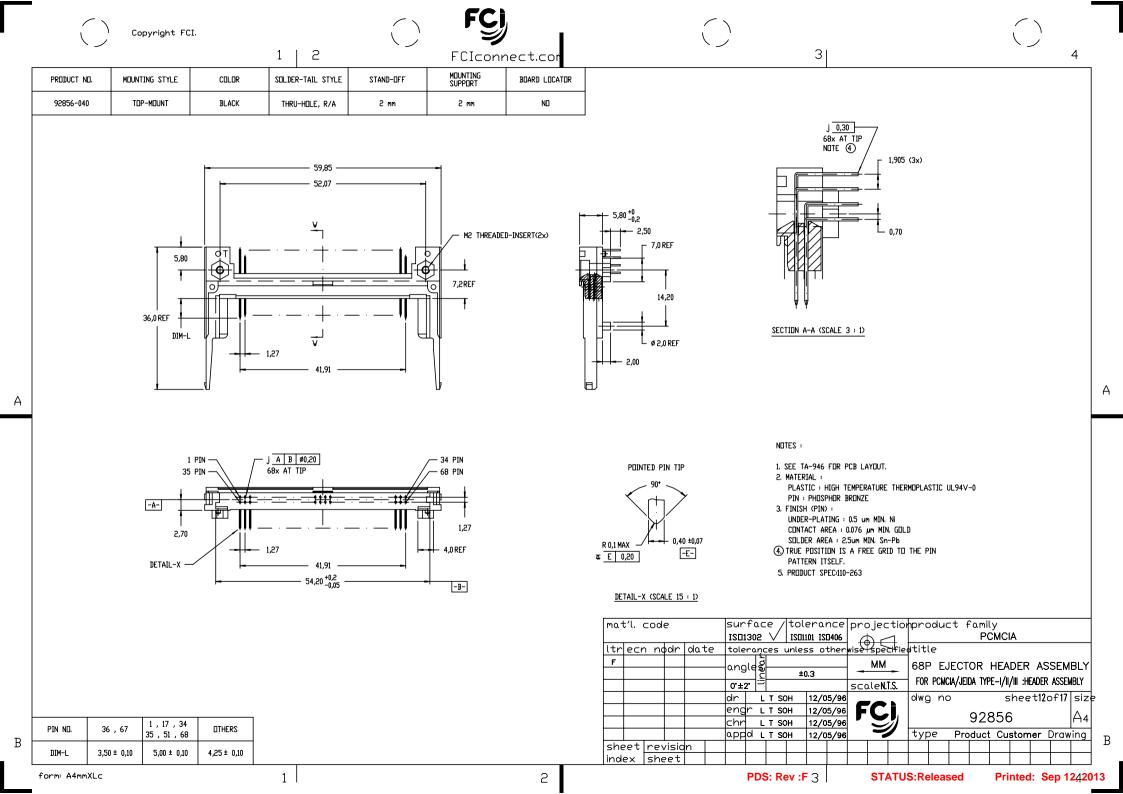
DIM-L

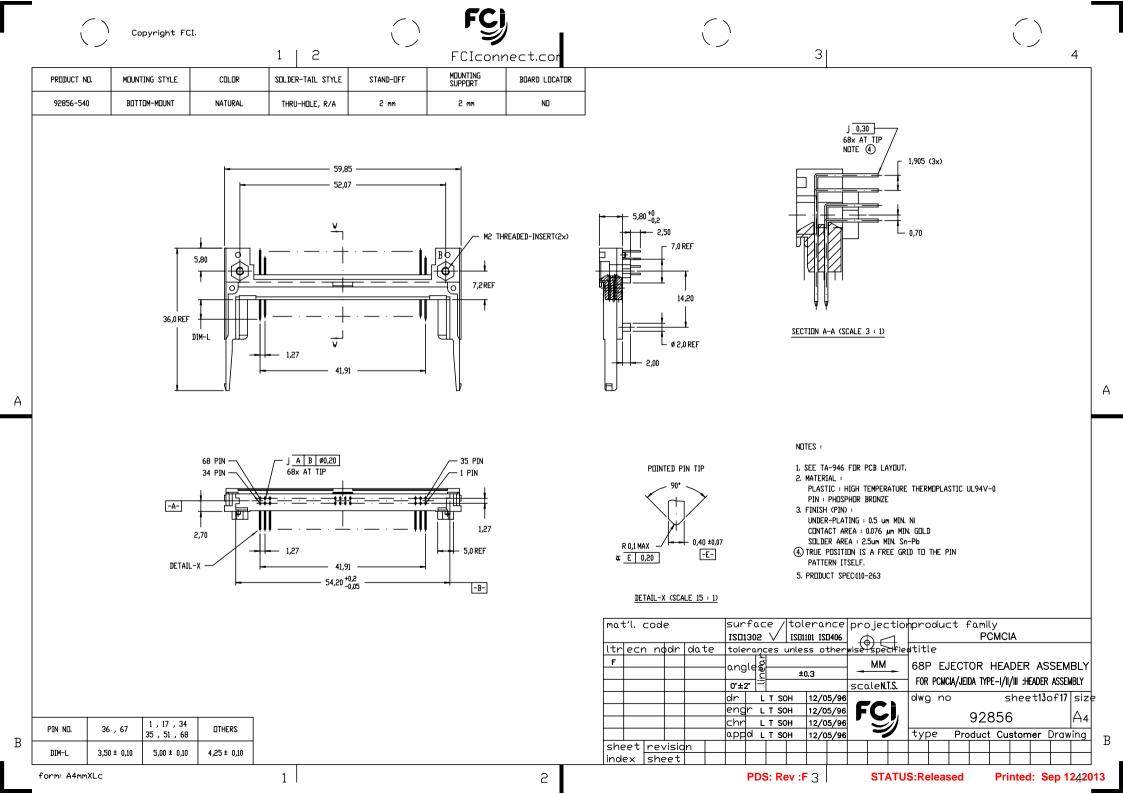


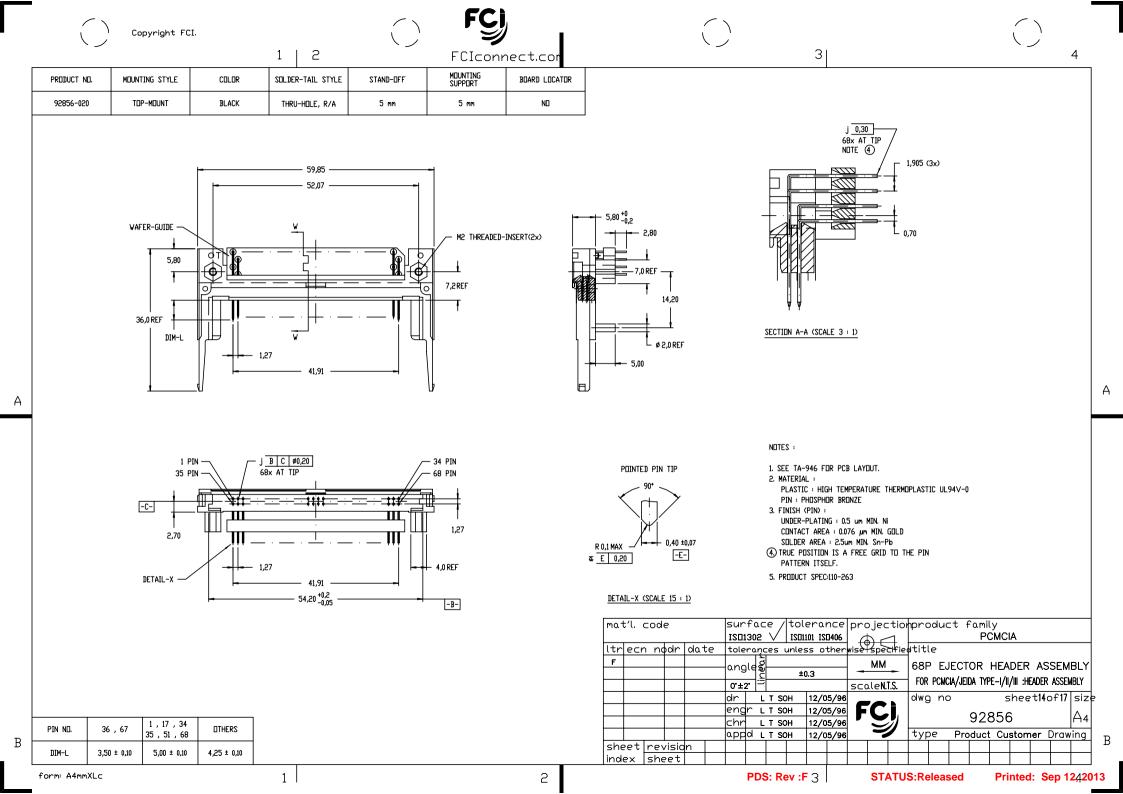


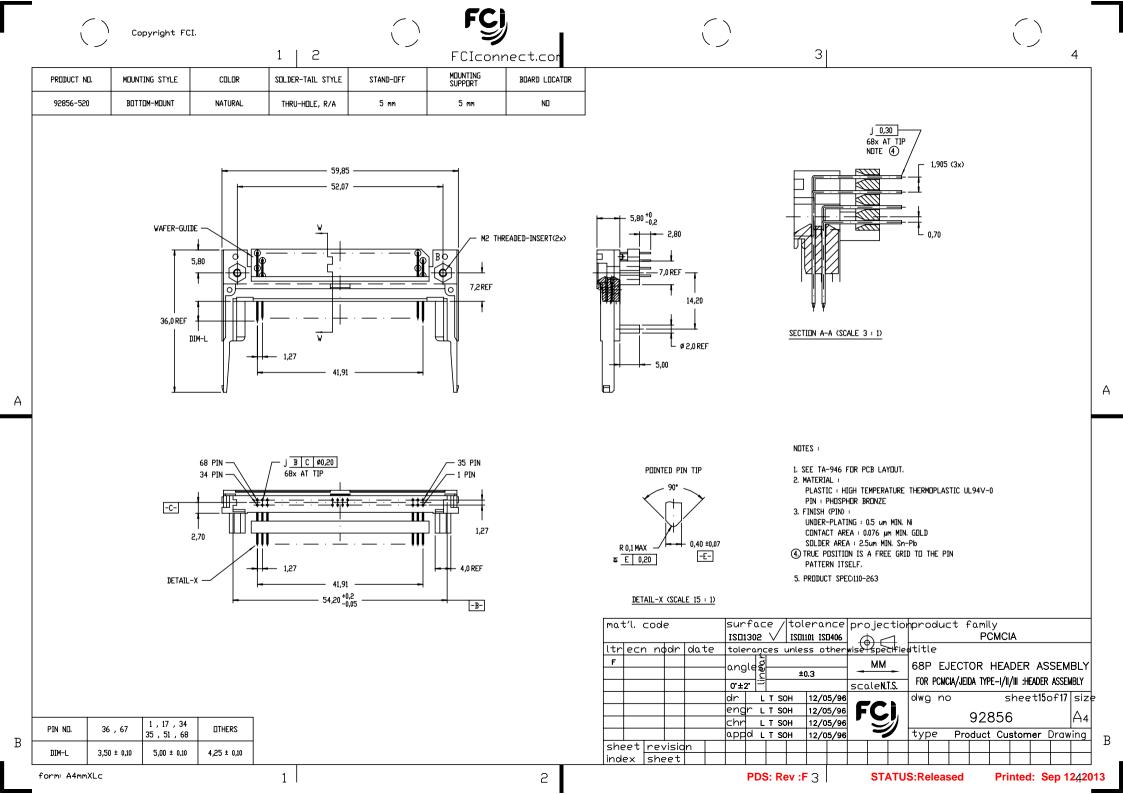














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- 34 PIN

1,27

-B-

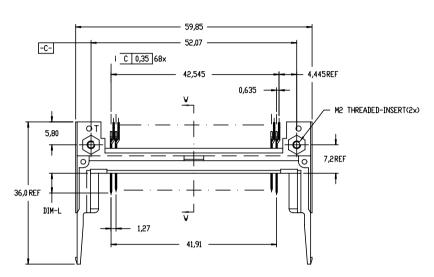
3

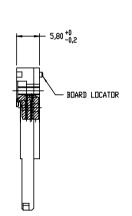
PRODUCT NO.	MOUNTING STYLE	COLOR	SOLDER-TAIL STYLE	STAND-OFF	MOUNTING SUPPORT	BOARD LOCATOR
92856-001	TOP-MOUNT	BLACK	SMT, STAGGERED (DOUBLE-ROW)	ND	ND	YES

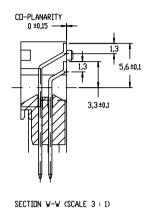
j A B Ø0,20

68x AT TIP

1 | 2







NOTES :

- 1. SEE TA-946 FOR PCB LAYDUT.
- 2. MATERIAL :

PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 PIN : PHOSPHOR BRONZE

- 3. FINISH (PIN) :
- UNDER-PLATING : 0.5 um MIN. Ni
- CONTACT AREA: 0.076 µm MIN. GOLD SOLDER AREA: 2.5um MIN. Sn-Pb
- 4. PRODUCT SPEC:110-263

mat	t'l. d	=od	2					1			projection product family													
					IS□1302 ✓ IS□1101 IS□406 tolerances unless otherw							\supset	1	PCMCIA										
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F					ang	اولخ	-	±	0.3		+	ММ	_	68P EJECTOR HEADER ASSI										
					0°±2	<u>-</u>					sco	ileN.	T.S.	FOR PCMCIA/JEIDA TYPE-I/II/III :HEADER ASSEMBI										
					dr	Ĺ	TS	ЭН	12/0	5/96				dwc	nc)		9	shee	t16	of17	si:		
					eng	ր լ	.TS	T SOH 12/05/96		12/05/96		12/05/96		FC					92	0 5 6				_
					chr	L	. T SC	ЭН	12/0	5/96			7				92	000)			 4		
					۵рр	dι	. T SC	T SOH		5/96		<i>-</i>		tyr	oe -	Pro	duct	t Cu	ston	ner	Draw	ing		
sheet		rev	isio/	n																				
ind	ex	she	et																					

PIN NO.	36 , 67	1 , 17 , 34 35 , 51 , 68	DTHERS
DIM-L	3,50 ± 0,10	5,00 ± 0,10	4,25 ± 0,10

В

form: A4mmXLc

2,70

2

PDS: Rev :F 3

STATUS:Released

Printed: Sep 1242013

В

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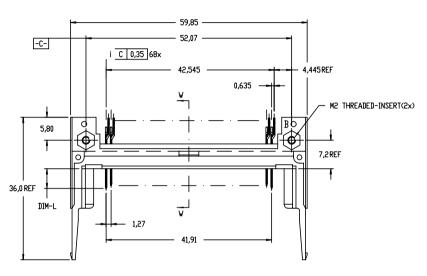
- 35 PIN

1,27

-B-

3

2 MOUNTING SUPPORT PRODUCT NO. MOUNTING STYLE COLOR SOLDER-TAIL STYLE STAND-OFF BOARD LOCATOR SMT. STAGGERED BOTTOM-MOUNT ND NΠ YES 92856-501 NATURAL (DOUBLE-ROW)



j A B Ø0,20

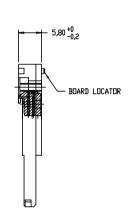
54,20 ^{+0,2} _{-0,05}

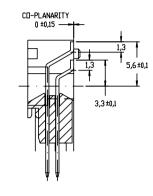
68x AT TIP

68 PIN

2,70

-A-





SECTION W-W (SCALE 3 : 1)

NOTES :

- 1. SEE TA-946 FOR PCB LAYOUT.
- 2. MATERIAL :

PLASTIC : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 PIN : PHOSPHOR BRONZE

3. FINISH (PIN) :

UNDER-PLATING : 0.5 um MIN. Ni CONTACT AREA: 0.076 µm MIN. GOLD

SOLDER AREA : 2.5um MIN. Sn-Pb

4. PRODUCT SPEC:110-263

mat'l code surface / to																									
mat	t'l. d	cod:	e			surface / tolerance								projectionproduct family											
						IS□1302							PCMCIA												
ltr	ecr	n no	dr	dat	e	tole	rar	ices	un	les	s 0	ther	wise specificatitle												
F						anc	gles							ММ		68P EJECTOR HEADER ASSEMBLY									
						ω, ιξ	Ϊ.	žL_		±0.	£0.3		_		_	FOR PCMCIA/JEIDA TYPE-I/II/III :HEADER ASSEMB									
						O°±:	2" -	7					sco	ileN.	T.S.	FUR FUNCIA/JEIDA TIPE-I/II/III : HEADER ASS							ASSEN	IBLT	
						dr		LT	r soh 1		12/0	5/96			_	dwg no				9	of 17	siz			
						eng	r	LT	SOH		12/05/96		12/05/96		FCj		, Ī.	9285					>		١, ,
						chr		LT	SOH		12/0	5/96							920	000)			Α4	
						app	d	LT	SOH		12/0	5/96		<u> </u>		typ	oe .	Pro	duct	t Cu	stom	er l	Draw	ing	
she	et	rev	/isio	n																					
inde	ex	she	et																						

1 , 17 , 34 PIN ND. 36 , 67 DTHERS 35 , 51 , 68 3,50 ± 0,10 DIM-L 5,00 ± 0,10 4,25 ± 0,10

PDS: Rev :F 3

STATUS:Released

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form: A4mmXLc

2